

Substrate-Like PCB Market - Forecasts from 2019 to 2024

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Abstracts

Global susbtrate-like PCB (SLP) market is estimated to witness a CAGR of 27.94% to reach US\$6,622.320 million in 2024 from US\$1,509.983 million in 2018. Substrate like PCB is high-end PCB that has a higher interconnect density per unit area as compared to the traditional HDI PCB. The demand for substrate like PCB is growing on account of its ability to enable faster transmission while simultaneously giving the manufacturers more freedom to design their product. Moreover, the rising trend of miniaturization of electronic devices coupled with the rising demand for electronic products like smartphones, tablets across the globe along with the growing electronics industry are some other key factors propelling the demand for PCBs which is expected to drive the substrate like PCB market over the coming years. Increasing R&D activities for technological advancements are anticipated to further widen up the market growth opportunities for substrate like PCBs during the forecast period.

The market has been segmented on the basis of line/space, technology, industry vertical and geography. By line/space, 25/25µm and 30/30µm are projected to grow at a significant rate on account of its wide application in consumer electronic devices. By industry vertical, consumer electronics is anticipated to hold a substantial market share owing to the rising demand for consumer electronics around the globe. Geographically, the Asia-Pacific is projected to hold a significant amount of share during the forecast period due to the rising use of electronic goods along with the growing communication infrastructure industry in the region.

DRIVERS

Increasing demand for miniature and effective electronic devices.



Growing electronics industry.

INDUSTRY UPDATE

In June 2019, TTM Technologies, Inc. agreed to acquire certain manufacturing and intellectual property assets from i3 Electronics, Inc. with an aim to strengthen its PCB capabilities and IP portfolio.

In April 2018, TTM Technologies Inc., acquired Anaren Inc.

The major players profiled in the substrate-like PCB market include AT&S, Zhen Ding Technology, TTM Technologies Inc., Samsung Electro-Mechanics, Unimicron Corporation, Korea Circuit, Ibiden Ltd., Daeduck Gds Co Ltd, Kinsus Interconnect Technology Corporation, and Compeq Co. Ltd.

Segmentation

The substrate-like PCB market has been analyzed through the following segments:

By Line/Space

25/25µm and 30/30µm

Less Than 25/25 µm

By Technology

Laser Direct Imaging

Automated Optical Inspection

Automated Optical Shaping

By Industry Vertical

Consumer Electronics

Communication and technology



| Automotive |
|-------------------------------|
| Military, Defense & Aerospace |
| Healthcare |
| Industrial |
| By Geography |
| North America |
| USA |
| Canada |
| Mexico |
| South America |
| Brazil |
| Argentina |
| Others |
| Europe |
| Germany |
| France |
| United Kingdom |
| Spain |
| Others |

Middle East and Africa





| Saudi Arabia | | |
|--------------|--|--|
| Israel | | |
| Others | | |
| Asia Pacific | | |
| China | | |
| Japan | | |
| South Korea | | |
| India | | |
| Others | | |



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